

KB2835CGKD

3.81 mm x 19.05 mm LED Light Bar

DESCRIPTIONS

- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- · Uniform light emitting area
- Low current operation
- Easily mounted on P.C. boards
- Flush mountable
- Excellent on/off contrast
- · Can be used with panels and legend mounts
- RoHS compliant

APPLICATIONS

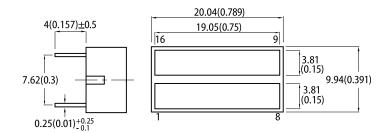
- · Home and smart appliances
- · Display time and digital combination
- · Industrial and instrumental applications
- Numeric status

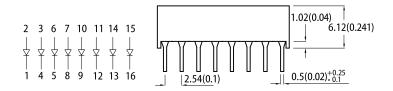
ATTENTION

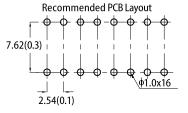
Observe precautions for handling electrostatic discharge sensitive devices



PACKAGE DIMENSIONS







- All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to change
- without prior notice.

SELECTION GUIDE

Part Number	Part Number Emitting Color Lens T	Long Time	Iv (mcd) @ 20mA [1]	
Part Number		Lens Type	Min.	Тур.
KB2835CGKD		Croon Diffused	20	50
KB2633CGKD	Green (AlGaInP) Green Diffused *8	*17		

Notes: 1. Luminous intensity / luminous Flux: +/-15%. * Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Val	ue	Unit
r ai ailletei	Symbol	Emitting Color	Тур.	Max.	Uill
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Green	574	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Green	570	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Green	20	-	nm
Capacitance	С	Green	15	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Green	2.1	2.5	V
Reverse Current (V _R = 5V)	I _R	Green	-	10	μΑ

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit
Power Dissipation	P _D	75	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +85	°C
Storage Temperature	T _{stg}	-40 to +85	°C
DC Forward Current	I _F	30	mA
Peak Forward Current	I _{FM} ^[1]	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Lead Solder Temperature [2]		260°C For 3-5 Seconds	

Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)

2. Forward voltage: ±0.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

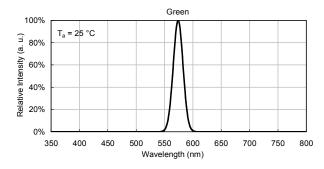
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



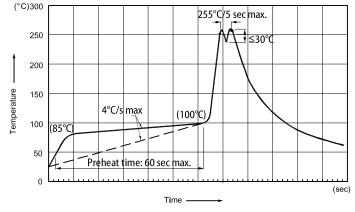
TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH



GREEN Forward Current vs. Luminous Intensity vs. Forward Current Derating Curve Luminous Intensity vs. Forward Voltage Forward Current **Ambient Temperature** 50 2.5 50 2.5 Luminous intensity normalised at Permissible forward current (mA) -uminous intensity normalised at $T_a = 25$ °C T_a = 25 °C Forward current (mA) 40 2.0 40 2.0 ပွ 30 1.5 30 1.5 МĀ $T_a = 25$ 20 20 1.0 1.0 20 10 0.5 10 0.5 0 0.0 0 0.0 2.5 20 40 60 80 1.9 2.1 2.3 0 10 20 30 40 50 -40 -20 0 -40 -20 0 20 40 60 80 100 1.5 1.7 Forward voltage (V) Forward current (mA) Ambient temperature (°C) Ambient temperature (°C)

RECOMMENDED WAVE SOLDERING PROFILE



Notes:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2. Peak wave soldering temperature between 245°C ~ 255°Cfor 3 sec (5 sec max).
- 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5. SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass.
 7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes

- 1. Through-hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1. Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning because they may damage the plastic
- 3. The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
- 4. When water is used in the cleaning process, Immediately remove excess moisture from the component with forced-air drying afterwards.